

Filename: PMP9013A\_BOM.xls

Date: 7/2/2013

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COUNT	RefDes	Value	Description	Size	Part Number	Mfr
4	FB1-4	500	Bead, Ferrite, 2000mA, 60m-ohm	1206	MI1206L501R-10	Steward
5	C3 C5-8	0.01uF	Capacitor, Ceramic, 100V, X7R, 10%	603	Std	STD
1	C35	0.01uF	Capacitor, Ceramic, 100V, X7R, 10%	603	Std	Std
1	C34	0.022uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
1	C12	0.1uF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
3	C13-14 C31	0.47uF	Capacitor, Ceramic, 16V, X7R, 10%	603	Std	Std
3	C1 C9 C29	1000pF	Capacitor, Ceramic, 100V, X7R, 10%	603	Std	STD
2	C21 C36	1uF	Capacitor, Ceramic, 16V, X7R, 10%	603	Std	Std
1	C32	330pF	Capacitor, Ceramic, 50V, C0G, 10%	603	Std	Std
1	C30	820pF	Capacitor, Ceramic, 16V, X7R, 10%	603	Std	Std
1	C33	DNP	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C2 C10	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	805	Std	STD
2	C22 C26	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	805	Std	STD
1	C27	1uF	Capacitor, Ceramic, 25V, X7R, 10%	805	Std	Std
2	C4 C11	1000pF	Capacitor, Ceramic, 2kV, X7R, 15%	1210	Std	STD
2	C24-25	1uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	Std	STD
3	C16-18	47uF	Capacitor, Ceramic, 10V, X5R, 15%	1210	Std	Std
1	C15	2200pF	Capacitor, Ceramic, 2KV, X7R, 15%	1812	Std	Std
1	C28	22uF	Capacitor, Aluminum, 25V, 20%	5x5.8mm	EEE-FK1E220R	Panasonic
2	C19-20	330uF	Capacitor, Aluminum, 6.3V, 20%	0.260 x 0.276 inch	EEE-FK0J331XP	Panasonic
1	C23	47uF	Capacitor, Aluminum, 63V, ±20%	0.328 x 0.390 inch	EEE-FK1J470P	Panasonic
2	J1-2	5520252-4	Connector, Jack, Modular, 8 POS	0.705 x 0.820 inch	5520252-4	AMP
2	D12 D14	1N4148W	Diode, Signal, 300-mA, 75-V, 350-mW	SOD-123	1N4148W-7-F	Diodes
1	D19	BAT54S	Diode, Dual Schottky, 200mA, 30V	SOT323	BAT54S	On Semi
3	D16-18	White	Diode, LED, White, 5mA, 85mcd	0.049 x 0.126 inch	23-21C/T1D-	Everlight
2	D13 D15	MBR0530	Diode, Schottky, 0.5A, 30V	SOD-123	MBR0530T1G	On Semi
1	D11	MURS120T3G	Diode, UltraFast Rectifier, 1-A, 200-V	SMB	MURS120T3G	On Semi
9	D1-5 D7-10	B2100	Diode, Schottky, 2-A, 100-V	SMB	B2100	STD
1	D6	SMAJ58A	Diode, TVS, 58-V, 1W	SMA	SMAJ58A	Diodes
4	J4-J7	PEC02SAAN	Header, Male 2-pin, 100mil spacing	0.100 inch x 2	PTC36SAAN	Sullins
1	L1	3.3uH	Inductor, SMT, 1.9A, 80 milliohm	4x4mm	LPS4018-332ML	Coilcraft
1	L2	0.33uH	Inductor, SMT, 19.2A, 3.52 milliohm	5.3x5.5 mm	XAL5030-331ME	Coilcraft

4	U1-4	PC357N4J000F	Photocoupler, 300-600% CTR, 3.75KV Isolation	MF4	PC357N4J000F	Sharp
1	U6	TCMT1107	IC, Photocoupler, 3750VRMS, 80-160% CTR	MF4	TCMT1107	Vishay
2	R15 R18	1.5K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R26-27	10	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R37	10K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R39	13.7K	Resistor, Chip, 1/16W, 1%	603	Std	Std
4	R11-13 R17	15K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R14 R33	1K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R19 R22	24.9K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R34	3.65K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R29	332	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R32	365	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R16	392K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R30	4.99K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R38	41.2K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R21	475K	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R35	49.9	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R36	604	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R24	63.4	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R20	15K	Resistor, Chip, 1/4W, 5%	1206	Std	Std
1	R31	0.1	Resistor, Chip, 1/2W, 1%	2010	Std	Std
1	R28	10	Resistor, Chip, 1W, 5%	2512	Std	Std
1	R6	10k	Resistor, Chip, 1/16W, 1%	603	Std	STD
1	R4	237k	Resistor, Chip, 1/16W, 1%	603	Std	STD
1	R25	34.8K	Resistor, Chip, 1/16W, 1%	603	Std	Std
8	R1-3 R5 R7-10	75	Resistor, Chip, 1/16W, 1%	603	Std	STD
1	R23	10	Resistor, Chip, 1/10W, 5%	805	Std	STD
			Switch, SPST, PB Momentary, Sealed			
1	S1		Washable	0.245 X 0.251 inch	KT11P2JM34LFS	C & K
2	J3 J8	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED555/2DS	OST
1	U7	TLV431A	IC, Shunt Regulator, 6V, 10mA, 1%	SOT23-5	TLV431ACDBVR	TI
2	TP1 TP3	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
3	TP2 TP4 TP6	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone
1	TP8	5012	Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
2	TP5 TP7	5013	Test Point, Orange, Thru Hole	0.125 x 0.125 inch	5013	Keystone
			IC, IEEE 802.3 AT PoE Interface & Green Mode			
1	U5	TPS23752PWP	DC-DC Controller	HTSSOP	TPS23752PWP	TI

2	Q3-4	MMBT3906	Trans, PNP, 40V, 200mA, 225mW	SOT23	MMBT3906	On Semi
1	Q2	Si7898DP	MOSFET, NChannel, 150V, 4.8A, 85 milliohm	PWRPAK S0-8	Si7898DP	Vishay
1	Q1	CSD18503Q5A	MOSFET, NChan, 40V, 19A, 6.2 millohm	PWRPAK S0-8	CSD18503Q5A	Vishay
1	T1	749022011	Transformer, PoE Plus Gigabit Transfomer Modules	S024	749022011	Pulse
1	T2	PA6399-AL	Transformer, SMT Flyback for PoE/PD, 22W, 5V, 4.5A	20.6x30 mm	PA6399-AL	Coilcraft

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
  2. These assemblies must be clean and free from flux and all contaminants.  
Use of no clean flux is not acceptable.
  3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
  4. Ref designators marked with an asterisk (\*\*\*) cannot be substituted.  
All other components can be substituted with equivalent MFG's components.
  5. Insert shorting jumper on J4, J7, and J11

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